

✓ On Page 5, line 3, please replace the word "conductive" with --conductive--.

✓ On Page 10, line 7, please replace the work "protect" with --protected--.

REMARKS

✓ Claims 1-25 are pending in this application.

✓ Claims 1-25 have been finally rejected.

For the convenience of the Examiner, the Applicant's remarks herein will be addressed in turn as set forth in the Office Action. Reconsideration and withdrawal of the rejection is respectfully requested.

I. REJECTIONS UNDER 35 U.S.C. §103(a)

A. Claims 1, 3-9 and 11-17 stand rejected under 35 U.S.C. §103(a) as obvious over U.S. Pat. No. 3,993,845 to Greenberg et al. (hereafter referred to as "Greenberg") in view of Applicant's admitted state of the art (specification, page 1, line 8 - pg. 9, line 26). Applicant respectfully traverses this rejection for the reasons set forth below.

The present invention teaches a process improvement in printed circuit board manufacture. Claim 1 recites a process for providing a protective coating on metal conducting surfaces formed on a bare board in the manufacture of printed circuit boards, comprising the steps of contacting the metal surface elements with an aqueous displacement plating composition which comprises silver ions and a multidentate complexing agent in solution in an aqueous vehicle at a pH of from 2 to 12 to form a silver coating on the metal surface elements. Greenberg teaches a method of preparing a metallic copper-silver film on a non-metallic transparent substrate. The method of Greenberg teaches that the metallic copper-silver film is applied to transparent articles, specifically large sheets or plates of flat